



To the Honorable Commissioner

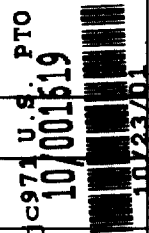
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with the attached original documents or copy thereof.

1. Name of conveying party(ies):
 Hwa-sung Rhee Nae-In Lee
 Geum-Jong Bae
 Tae-Hee Choe
 Sang-su Kim
 10-23-01

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
 Name: Samsung Electronics, Co., Ltd.
 Internal Address: _____



3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Street Address: 416, Maetan-dong, Paldal-gu,
Suwon-city, Kyungki-do, Republic of Korea
 City: _____ State _____ ZIP _____

Execution Date: September 17, 2001

Additional name(s) & address attached? Yes No

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: September 17, 2001

A. Patent Application No.(s)
10/001619

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: Steven M. Mills
 Internal Address: MILLS & ONELLO LLP
 Street Address: Eleven Beacon Street, Suite 605
 City: Boston State MA ZIP 02108

6. Total number of applications and registrations involved 1

7. Total fee (37 CFR 3.41)..... \$40.00
 Enclosed
 Authorized to be charged to deposit account

8. Deposit Account Number: _____
(Attach duplicate copy of this page if paying by deposit account)

12/11/2001 6TOM11 00000132 10001619 DO NOT USE THIS SPACE

9. Statement and signature:
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Steven M. Mills 36.610
Name of Person Signing

Steven M. Mills
Signature

10/23/01
Date

Total number of pages including cover sheet, attachments, and document 3

ASSIGNMENT

We, Hwa-Sung Rhee, of 1679-2, Bongchun 6-dong, Kwanak-ku, Seoul, Republic of Korea; Geum-Jong Bae, of 304-1402, LG Village Apt., Keungok-dong, Kwonsun-ku, Suwon, Kyunggi-do, Republic of Korea; Tae-Hee Choe, 570-41, Younnam-dong, Mapo-ku, Seoul, Republic of Korea; Sang-Su Kim, of 72-2 Hupyoung-ri, Hasung-myeon, Kimpo-shi, Kyunggi-do, Republic of Korea; and Nae-In Lee, of 117-1504, Kwanak Hyundai Apt., Bongchun 3-dong, Kwanak-ku, Seoul, Republic of Korea, having invented improvements in CMOS SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME, described in an application for Letters Patent of the United States, executed by us on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

First or Sole Inventor:

Signature: HwaSung Rhee
Hwa-sung Rhee

Date: Sept. 17, 2001

Second Joint Inventor:

Signature: GeumJong Bae
Geum-Jong Bae

Date: Sept. 17, 2001

Third Joint Inventor:

Signature: Tae-Hee Choe
Tae-Hee Choe

Date: Sept. 17, 2001

Fourth Joint Inventor:

Signature: Sang-su Kim
Sang-su Kim

Date: Sept. 17, 2001

Fifth Joint Inventor:

Signature: Nae-In Lee
Nae-In Lee

Date: Sept. 17, 2001